

SELECTIVELY COATING BOND PADS

Abstract of the Disclosure

Solder ball bond pads and wire bond pads may be selectively coated so that the wire bond bond pads have a thicker gold coating than the solder ball bond pads. This
5 may reduce the embrittlement of solder ball joints while providing a sufficient thickness of gold for the wire bonding process. In general, gold coatings are desirable on electrical contact surfaces to prevent oxidation. However, the thickness of gold which is necessary on solder
10 ball bond pads may be less and excessive gold may be disadvantageous. Thus, by masking the solder ball bond pads during the gold coating of the wire bond bond pads, a differential gold thickness may be achieved which is more advantageous for each application.